

Product Advisory (PA)

Subject: Change of the standard interior label of Renesas Electronics

Publication Date: December 1, 2022

Effective Date: Refer to Appendix A to D

Revision Description:

Initial Release

Description of Change:

Renesas Electronics will update and streamline the standard interior labels in shipments for all products in conjunction with our systems integration plan.

Kindly refer to Appendix A to D for comparison on the current and new standard labels.

Materials related to 2D barcode specifications is available upon request.

Affected Product List:

All products, including legacy Intersil, IDT, Dialog and Renesas except custom-labeled products.

Reason for Change:

To integrate company-wide standard labels through the integration of SCM systems, including logistic systems.

Impact on Fit, Form, Function, Quality & Reliability:

This change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Qualification Status: Not applicable

Sample Availability Date: Not applicable

Device Material Declaration: Not applicable

Questions or requests pertaining to this change notice, including additional data, must be sent to Renesas within 30 days of the publication date.

APPENDIX A: LEGACY INTERSIL PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item	
① Lot Combine Information	
② D/N (Device Name)	
③ SPN (SAP Parts Name)	
④ CPN / CPN2 (Customer Parts No.)	
⑤ PID (Pack ID)	
⑥ QTY	
⑦ MG LOT (Manufacturing Lot No.)	
⑧ S.Lot (Shipping Batch Lot)	
⑨ SQTY (Wafers Q'ty)	
⑩ OSAT Code	
⑪ Expiry Date	
⑫ Seal Date	
⑬ Halogen Free	
⑭ Pb-Free Logo Mark	
⑮ Pb-Free with Detail Rank Information	
⑯ China RoHS (Logo Mark or "Blank")	
⑰ Country of Origin	
⑱ PCB On Board Reflow Rank (Peak Temp)	
⑲ Labeling Date	
⑳ Condition after opening (MSL Rank)	
㉑ RoHS Exempt (RoHS or RoHS Exempt)	
㉒ REACH Certified (REACH or "Blank")	
㉓ UL Certified	
㉔ UL Rank	
㉕ Wafer Size	
㉖ Partial Lot Sign	
㉗ Mix Lot Sign	

ABC0001Z ABC0002A ABC0002B

① 2234 2235 2235

2000 1000 1000

⑪ EXP.D 2024/08/30

⑫ Seal Date 2022/09/01

⑬ Halogen Free

⑭ 2022/09/02

RENESAS

⑮ T: 260

⑯ RoHS Exempt

⑰ MSL:3

⑱ REACH

⑲ MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

⑳ Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

② D/N RAA462111GBG

③ SPN RAA462111GBG#ACO AC0YE0100

④ CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

⑤ PID 223510100A-001 SIZE =12

⑥ QTY 4000 ㉖ PARTIAL ♦♦ ㉗ SQTY 2

⑦ MG LOT 2234ABC0001Z SC: AB

⑧ S.LOT YZWF00AA01 MIXED ★

100mm

ABC0001Z ABC0002A ABC0002B

2234 2235 2235

2000 1000 1000

EXP.D 2024/08/30

Seal Date 2022/09/01

Halogen Free

2022/09/02

RENESAS

T: 260

RoHS Exempt

MSL:3

REACH

MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

D/N RAA462111GBG

SPN RAA462111GBG#ACO AC0YE0100

CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

PID 223510100A-001 SIZE =12

QTY 4000 PARTIAL ♦♦ SQTY 2

MG LOT 2234ABC0001Z SC: AB

S.LOT YZWF00AA01 MIXED ★

42mm

Comparison before and after change for legacy INTERSIL products

Gap Points Current and New / Ex-ISL

For Finished Goods

For Wafer Sales

42mm

10mm

32mm

For Wafer Sales

Gap Points

☐ Added Items

PID (Traceability Control)

S.LOT (Traceability Control)
For Renesas Internal Use

Add RoHS / RoHS Exempt
(Display RoHS or RoHS Exempt)

Add China RoHS
(Display China RoHS Certified)

☐ Design Change Items

SPN (Orderable Parts No.)

CPN/CPN2 (Customer Parts No.)

Lot Combine Information

Country of Origin
(Manufacturing Country Info.)

PCB On Board Reflow Rank
(Peak Temperature)

MG LOT (Manufacturing Lot No.)

For additional information regarding this notice, please contact your regional change coordinator (below)

Americas: PCN-US@Renesas.COM Europe: PCN-EU@Renesas.COM Japan: PCN-JP@Renesas.COM Asia Pac: PCN-APAC@Renesas.COM

APPENDIX B: LEGACY IDT PRODUCTS

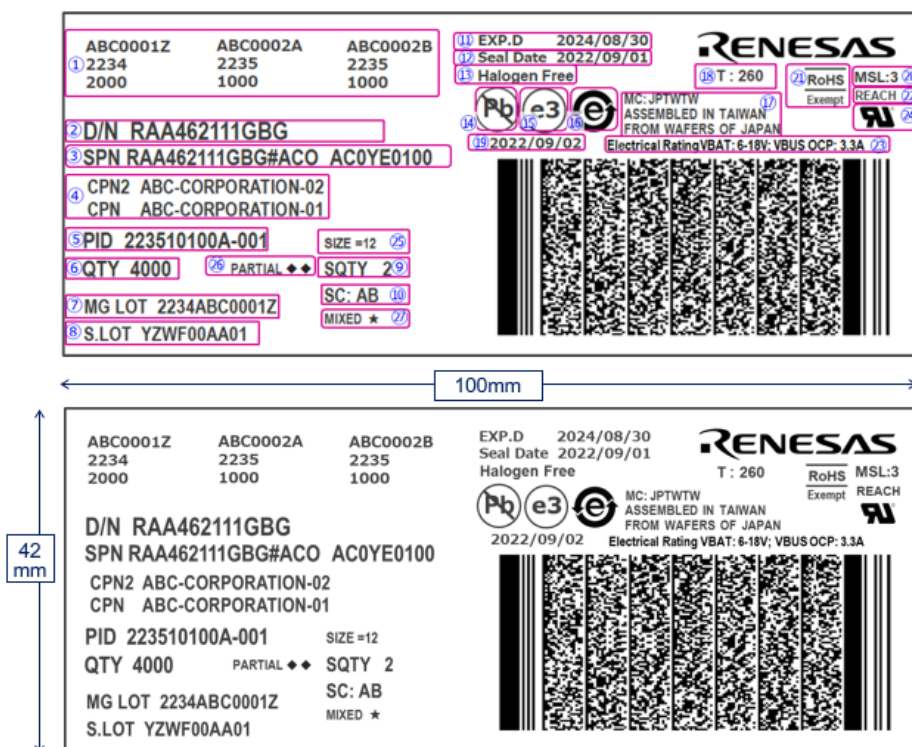
Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy IDT products

Gap Points Current and New / Ex-IDT

For Finished Goods

For Wafer Sales

➔

42mm

100mm

10mm

32mm

For
Wafer Sales

Gap Points

- **Added Items**
 - PID (Traceability Control)
 - S.LOT (Traceability Control)
 - For Renesas Internal Use
- **Design Change Items**
 - SPN (Orderable Parts No.)
 - Lot Combine Information
 - MG LOT (Manufacturing Lot No.)
 - Pb-Free's Logo Mark
 - Country of Origin (Manufacturing Country Info.)
 - PCB On Board Reflow Rank (Peak Temperature)

For additional information regarding this notice, please contact Idt-pcn@lm.renesas.com.

APPENDIX C: LEGACY DIALOG PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign

ABC0001Z ABC0002A ABC0002B

① 2234 2235 2235

2000 1000 1000

⑪ EXP.D 2024/08/30

⑫ Seal Date 2022/09/01

⑬ Halogen Free

⑭ 2022/09/02

RENESAS

⑮ T: 260

⑯ RoHS Exempt

⑰ MSL:3

⑱ REACH

⑲ MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

⑳ Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

② D/N RAA462111GBG

③ SPN RAA462111GBG#ACO AC0YE0100

④ CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

⑤ PID 223510100A-001 SIZE =12

⑥ QTY 4000 ㉖ PARTIAL ♦♦ ㉗ SQTY 2

⑦ MG LOT 2234ABC0001Z SC: AB

⑧ S.LOT YZWF00AA01 MIXED ★

100mm

ABC0001Z ABC0002A ABC0002B

2234 2235 2235

2000 1000 1000

EXP.D 2024/08/30

Seal Date 2022/09/01

Halogen Free

2022/09/02

RENESAS

T: 260

RoHS Exempt

MSL:3

REACH

MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

D/N RAA462111GBG

SPN RAA462111GBG#ACO AC0YE0100

CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

PID 223510100A-001 SIZE =12

QTY 4000 PARTIAL ♦♦ SQTY 2

MG LOT 2234ABC0001Z SC: AB

S.LOT YZWF00AA01 MIXED ★

42mm

Comparison before and after change for legacy DIALOG products

Gap Points Current and New / Ex-DLG

For Finished Goods

42mm

10mm

32mm

For Wafer Sales

100mm

For Finished Goods (Current)

(1) Batch No.: K123456
(10) Datecode: YYWWZZZ
(2) Quantity: 2600
C/P No.: DA9063-xH02
Reel Date: 21.11.2017
Reel No.: 1234567890

For Wafer Sales (Current)

P/N: D3034GAW0DWP024
Lot No.: PUT62.30
WFR No.: 1-26
Qty. WFR: 26
Qty. Die: 174464
ATTENTION: ELECTION DATE: 2022/09/02

For Finished Goods (New / Ex-DLG)

ABC0001Z ABC0002A ABC0002B
2234 2235 2235
2000 1000 1000

SPN RAA462111GBG#ACO
CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01
PID 223510100A-001
QTY 4000 SQTY 2
MG LOT 2234ABC0001Z
SLOT YZWF00A01

For Wafer Sales (New / Ex-DLG)

SPN RAA462111GBG#ACO
CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01
PID 223510100A-001
QTY 4000 SQTY 2
MG LOT 2234ABC0001Z
SLOT YZWF00A01

Gap Points

☐ Added Items

- PID (Traceability Control)
- EXP. Date (Traceability Control) For Renesas Internal Use
- S.LOT (Traceability Control) For Renesas Internal Use

☐ Design Change Items

- Renesas Logo Mark
- SPN (Orderable Parts No.)
- CPN/CPN2 (Customer Parts No.)
- MG LOT (Manufacturing Lot No.)
- Lot Combine Information
- Country of Origin (Manufacturing Country Info.)
- PCB On Board Reflow Rank (Peak Temperature)
- SC (Test Supplier Code)

For additional information regarding this notice, please contact your Renesas sales representative.

APPENDIX D: LEGACY RENESAS PRODUCTS

Effective Date: April 1, 2024

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign

ABC0001Z ① 2234 2000	ABC0002A 2235 1000	ABC0002B 2235 1000
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② D/N RAA462111GBG

③ SPN RAA462111GBG#ACO AC0YE0100

④ CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

⑤ PID 223510100A-001 SIZE =12 ㉕

⑥ QTY 4000 ㉖ PARTIAL ♦♦ ㉗ SQTY 2 ㉗

⑦ MG LOT 2234ABC0001Z SC: AB ㉔

⑧ S.LOT YZWF00AA01 MIXED ★ ㉕

⑪ EXP.D 2024/08/30
⑫ Seal Date 2022/09/01
⑬ Halogen Free

⑭ T: 260 ㉑ RoHS MSL:3 ㉑
Exempt REACH ㉒

⑰ MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

⑲ 2022/09/02 Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A ㉓

100mm

42
mm

ABC0001Z 2234 2000	ABC0002A 2235 1000	ABC0002B 2235 1000
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D/N RAA462111GBG

SPN RAA462111GBG#ACO AC0YE0100

CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

PID 223510100A-001 SIZE =12

QTY 4000 PARTIAL ♦♦ SQTY 2

MG LOT 2234ABC0001Z SC: AB

S.LOT YZWF00AA01 MIXED ★

EXP.D 2024/08/30
Seal Date 2022/09/01
Halogen Free

T: 260 RoHS MSL:3
Exempt REACH

MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

2022/09/02 Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

Comparison before and after change for legacy RENESAS products

Gap Points Current and New / Renesas Japan (REL)



Gap Points

Design Change Items

- Pb-Free's Logo Mark
- PCB On Board Reflow Rank (Peak Temperature)
- Customer Parts No. (Display Name Change)
PN/PN2 => CPN/CPN2
- MG LOT (Display Name Change)
T/C => MG LOT
- PCN (Deleted Item)

For additional information regarding this notice, please contact your Renesas sales representative.